

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
P_{PK}	Peak Pulse Power ($t_p=8/20\mu s$)	20	W
I_{PP}	Peak Current ($t_p=8/20\mu s$)	3.0	A
T_{OP}	Operating Temperature	-40 to 125	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Characteristics ($T_{OP}=25^\circ C$)

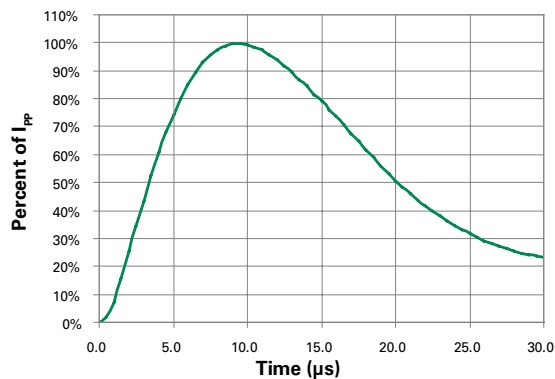
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}				5.3	V
Reverse Breakdown Voltage	V_{BR}	$I_R=1mA$	6.8	7.8	9.1	V
Reverse Leakage Current	I_{LEAK}	$V_R=5.3V$		<10	100	nA
Clamp Voltage ¹	V_C	$I_{PP}=1A$, $t_p=8/20\mu s$, Fwd			12.0	V
Dynamic Resistance ²	R_{DYN}	TLP, $t_p=100ns$, I/O to GND		0.7		Ω
ESD Withstand Voltage ¹	V_{ESD}	IEC 61000-4-2 (Contact)	± 20			kV
		IEC 61000-4-2 (Air)	± 30			kV
Diode Capacitance ¹	C_D	Reverse Bias=0V		0.35	0.5	pF

Note:

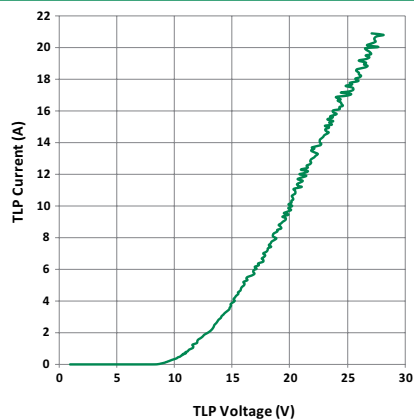
¹ Parameter is guaranteed by design and/or component characterization.

² Transmission Line Pulse (TLP) with 100ns width and 200ps rise time.

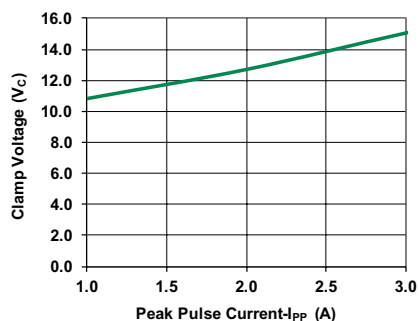
8/20 Pulse Waveform



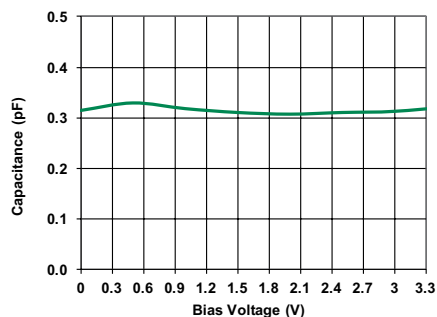
Transmission Line Pulsing(TLP) Plot



Clamping Voltage vs I_{PP}

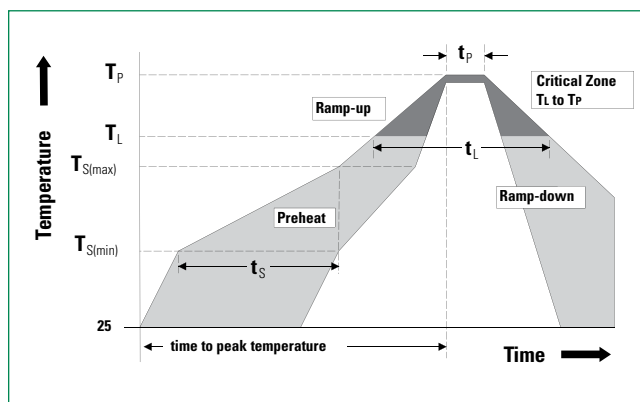


Capacitance vs. Reverse Bias



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Product Characteristics of 0201 Flipchip

Lead Plating	Sn
Lead Material	Copper
Substrate material	Silicon
Body Material	Silicon

Product Characteristics of SOD882

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Substrate material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0.

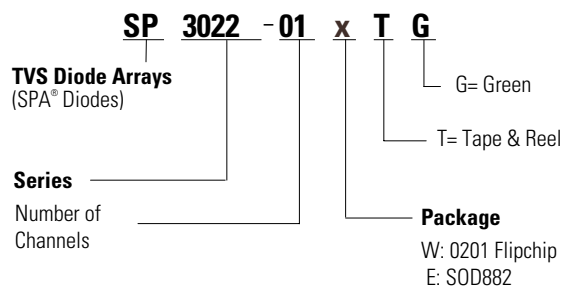
Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Ordering Information

Part Number	Package	Min. Order Qty.
SP3022-01WTG	0201 Flipchip	10000
SP3022-01ETG	SOD882	10000

Part Numbering System



Part Marking System

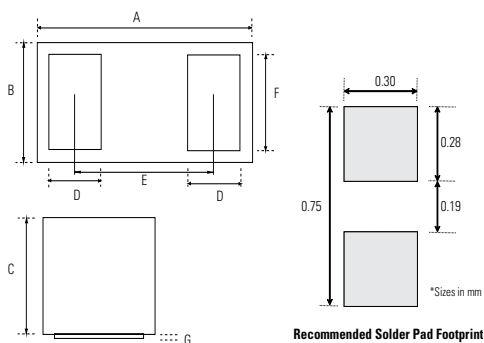


SP3022-01WTG



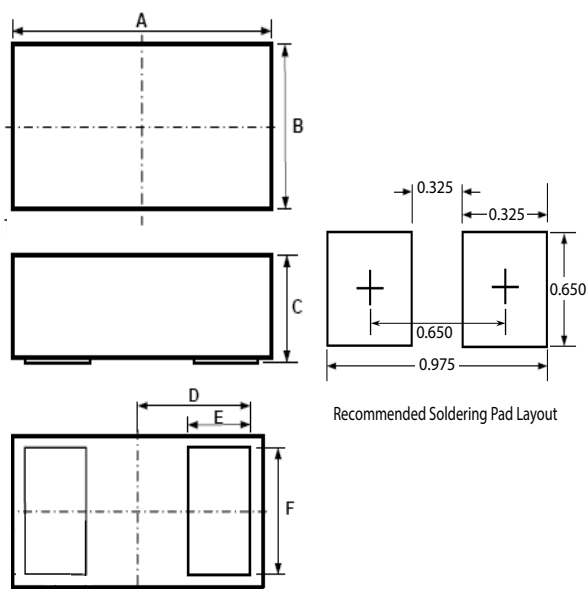
SP3022-01ETG

Package Dimensions — 0201 Flipchip



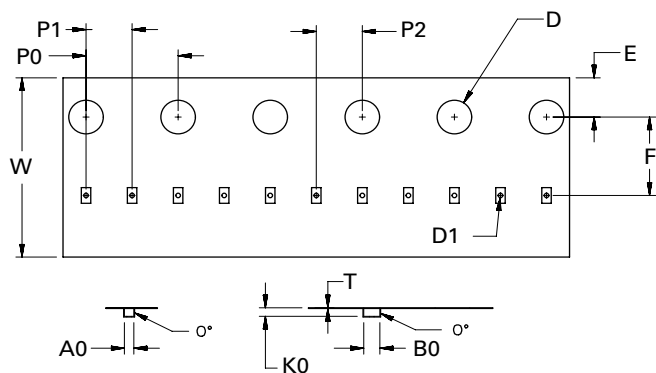
Symbol	0201 Flipchip					
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.605	0.630	0.655	0.0238	0.0248	0.0258
B	0.305	0.330	0.355	0.0120	0.0130	0.0140
C	0.265	0.290	0.315	0.0104	0.0114	0.0124
D	0.115	0.120	0.125	0.0045	0.0047	0.0049
E	-	0.4	-	-	0.0157	-
F	0.215	0.220	0.225	0.0085	0.0087	0.0089
G	0.008	0.011	0.014	0.0003	0.0004	0.0006

Package Dimensions — SOD882



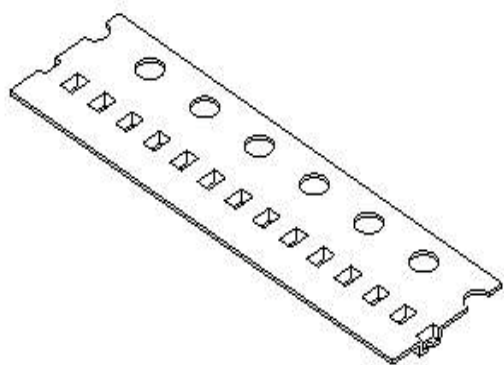
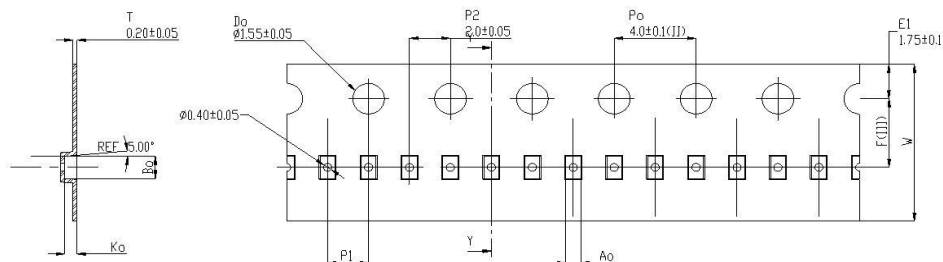
Symbol	Package	SOD882				
	JEDEC	MO-236				
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.95	1.00	1.10	0.035	0.039	0.043
B	0.50	0.60	0.70	0.020	0.024	0.028
C	0.40	0.50	0.60	0.016	0.020	0.024
D	0.45			0.018		
E	0.20	0.25	0.35	0.008	0.010	0.012
F	0.45	0.50	0.55	0.018	0.020	0.022

Embossed Carrier Tape & Reel Specification — 0201 Flipchip



Symbol	Millimeters
A0	0.41+/-0.03
B0	0.70+/-0.03
D	ø 1.50 + 0.10
D1	ø 0.20 +/- 0.05
E	1.75+/-0.10
F	3.50+/-0.05
K0	0.38+/-0.03
P0	4.00+/-0.10
P1	2.00+/-0.05
P2	2.00+/-0.05
W	8.00 + 0.30 -0.10
T	0.23+/-0.02

Embossed Carrier Tape & Reel Specification — SOD882



Symbol	Millimeters
A0	0.70+/-0.045
B0	1.10+/-0.045
K0	0.65+/-0.045
F	3.50+/-0.05
P1	2.00+/-0.10
W	8.00 + 0.30 -0.10